# PATENT ASSIGNMENT COVER SHEET

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| **SUBMISSION TYPE:** | NEW ASSIGNMENT |
| **NATURE OF CONVEYANCE:** | ASSIGNMENT |

**CONVEYING PARTY DATA**

| Name | Execution Date |
|---|---|
| HENKEL AG & CO. KGAA | 01/05/2023 |

**RECEIVING PARTY DATA**

| | |
|---|---|
| **Name:** | HARIMA CHEMICALS GROUP, INC. |
| **Street Address:** | NIHONBASHI SAKURADORI BLDG. 5TH FLOOR |
| **Internal Address:** | 3-8-4 NIHONBASHI, CHUO-KU |
| **City:** | TOKYO |
| **State/Country:** | JAPAN |
| **Postal Code:** | 103-0027 |

**PROPERTY NUMBERS Total: 8**

| Property Type | Number |
|---|---|
| **Patent Number:** | 8486498 |
| **Patent Number:** | 9427829 |
| **Patent Number:** | 9511453 |
| **Patent Number:** | 9682447 |
| **Patent Number:** | 10189121 |
| **Patent Number:** | 10376994 |
| **Application Number:** | 17675103 |
| **Patent Number:** | 11285569 |

**CORRESPONDENCE DATA**

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|---|---|
| **ATTORNEY DOCKET NUMBER:** | 0077527-000059 |
| **NAME OF SUBMITTER:** | STACEY PFLIEGER |

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|---|---|
| **SIGNATURE:** | /StaceyPflieger/ |
| **DATE SIGNED:** | 01/24/2023 |
| **Total Attachments: 2**<br>source=059assign#page1.tif<br>source=059assign#page2.tif | |

Attorney Docket No.: 0077527-000059

# ASSIGNMENT

THIS ASSIGNMENT, by HENKEL AG & CO. KGAA, a corporation duly organized under and pursuant to the laws of GERMANY and having a principal place of business at Henkelstrasse 67, Duesseldorf 40589, Germany (hereinafter referred to as "the Assignor"), witnesseth:

WHEREAS, the Assignor has the entire right, title and interest in and to certain new and useful inventions set forth in the U.S. Patents listed in attached Appendix I, and an unspecified amount of right, title and interest in and to certain new and useful inventions set forth in the U.S. Patents and U.S. Patent Application listed in attached Appendix II;

WHEREAS, Harima Chemicals Group, Inc., a corporation duly organized under and pursuant to the laws of JAPAN and having a principal place of business at Nihonbashi Sakuradori Bldg. 5th floor, 3-8-4 Nihonbashi, Chuo-ku, Tokyo 103-0027, JAPAN (hereinafter referred to as "the Assignee"), is desirous of acquiring, and does hereby acquire, the entire right, title, and interest in and to said U.S. Patents of the United States listed in attached Appendix I, and the unspecified amount of right, title and interest in and to said U.S. Patent Application and U.S. Patents of the United States listed in attached Appendix II.

NOW, THEREFORE, for good and sufficient consideration, the receipt of which is hereby acknowledged, the Assignor hereby confirms any prior assignment to Assignee, and to the extent that Assignor has not already done so, agrees to assign, and hereby does sell, assign, transfer, and set over, unto the Assignee, its successors, legal representatives, and assigns the entire right, title, and interest in and to the U.S. Patents of the United States listed in attached Appendix I, and the unspecified amount of right, title and interest in and to the U.S. Patent Application and U.S. Patents of the United States listed in attached Appendix II, any U.S. Patent(s) that may be granted therefor and thereon, and reissues, reexamination, and extensions of said U.S. patents, and all rights under the International Convention for the Protection of Industrial Property, the same to be held and enjoyed by the Assignee, for its own use and behoof and the use and behoof of its successors, legal representatives, and assigns, to the full end of the term of said U.S. Patent Application and U.S. Patents listed in the attached Appendices as fully and entirely as the same would have been held and enjoyed by the Assignor had this sale and assignment not been made;

AND for the same consideration, the Assignor hereby covenants and agrees to and with the Assignee, its successors, legal representatives, and assigns, that, at the time of execution of these presents, the Assignor is the sole and lawful owner of the entire right, title, and interest in and to the inventions set forth in said U.S. Patents of the United States listed in attached Appendix I, and the unspecified amount of right, title and interest in and to the inventions set forth in said U.S. Patent Application and U.S. Patents of the United States listed in attached Appendix II, and that the same is unencumbered, and that the Assignor has good and full right and lawful authority to sell and convey the same in the manner herein set forth;

AND for the same consideration, the Assignor hereby covenants and agrees to and with the Assignee, its successors, legal representatives, and assigns that the Assignor will, whenever counsel of the Assignee, or the counsel of its successors, legal representatives, and assigns, shall advise that any proceeding in connection with said U.S. Patent Application and U.S. Patents listed in the attached Appendices, or any reissue, reexamination, or extension to be obtained thereon, is lawful and desirable, sign all papers and documents, take all lawful oaths, and do all acts necessary or required to be done for the procurement, maintenance, enforcement, and defense of said U.S. Patent Application and U.S. Patents listed in the attached Appendices for said inventions, without charge to the Assignee, its successors, legal representatives, and assigns, but at the cost and expense of the Assignee, its successors, legal representatives, and assigns.

**HENKEL AG & CO. KGAA**

DATE: January 05, 2023

Signature: ______________________
Name/Title: Dr. Stefan Kucken, Corporate Director Legal

DATE: January 05, 2023

Signature: ______________________
Name/Title: Dr. Markus Semrau, Corporate Director Legal

## APPENDIX I

| Application No. | Filing Date | Title | Patent No. | Issue Date | Recorded Reel / Frame |
|---|---|---|---|---|---|
| | | | | | |
| 13/113,716 | May 23, 2011 | THERMALLY DECOMPOSABLE POLYMER COATED METAL POWDERS | 8,486,498 B2 | July 16, 2013 | 059357/0267 |
| 14/199,179 | March 6, 2014 | DI- OR POLY-FUNCTIONAL ELECTRON DEFICIENT OLEFINS COATED METAL POWDERS FOR SOLDER PASTE | 9,427,829 B2 | August 30, 2016 | 059357/0267 |
| 13/530,751 | June 22, 2012 | SOLDER PASTE COMPOSITION, A SOLDER PASTE AND A SOLDERING FLUX | 9,511,453 B2 | December 6, 2016 | 059357/0267 |
| 12/860,497 | August 20, 2010 | ORGANIC ACID- OR LATENT ORGANIC ACID-FUNCTIONALIZED POLYMER-COATED METAL POWDERS FOR SOLDER PASTES | 9,682,447 B2 | June 20, 2017 | 059357/0267 |
| 15/599,024 | May 18, 2017 | ORGANIC ACID-OR LATENT ORGANIC ACID-FUNCTIONALIZED POLYMER-COATED METAL POWDERS FOR SOLDER PASTES | 10,189,121 B2 | January 29, 2019 | 059357/0267 |

## APPENDIX II

| Application No. | Filing Date | Title | Patent No. | Issue Date | Recorded Reel / Frame |
|---|---|---|---|---|---|
| | | | | | |
| 10/554,274 | September 13, 2006 | SOLDERING MATERIAL BASED ON SN AG AND CU | 10,376,994 B2 | August 13, 2019 | 025326/0562 |
| 16/530,053 | August 2, 2019 | SOLDERING MATERIAL BASED ON SN AG AND CU | 11,285,569 B2 | March 29, 2022 | 025326/0562 |
| 17/675,103 | February 18, 2022 | SOLDERING MATERIAL BASED ON SN AG AND CU | | | 025326/0562 |